

RM6N800HD RM6N800T1 RM6N800T2

## N-Channel Super Junction Power MOSFET III

### **General Description**

The series of devices use advanced trench gate super junction technology and design to provide excellent RDS(ON) with low gate charge. This super junction MOSFET fits the industry's AC-DC SMPS requirements for PFC, AC/DC power conversion, and industrial power applications.

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- New technology for high voltage device
- Low on-resistance and low conduction losses
- small package
- Ultra Low Gate Charge cause lower driving requirements
- 100% Avalanche Tested
- ROHS compliant

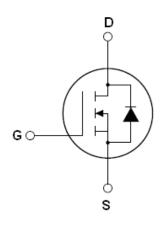
## **Application**

- Power factor correction (PFC)
- Switched mode power supplies(SMPS)
- Uninterruptible Power Supply (UPS)

### Package Marking And rdering Information

Device	Device Package	Marking	
RM6N800HD	TO-263	6N800	
RM6N800T2	TO-220	6N800	
RM6N800T1	TO-220F	6N800	

# $\begin{array}{c|cccc} V_{DS} & 800 & V \\ \hline R_{DS(ON)MAX} & 900 & m\Omega \\ \hline I_D & 6 & A \\ \hline \end{array}$



#### Schematic diagram







**TO-263** 

**TO-220** 

**TO-220F** 

Table 1. Absolute Maximum Ratings (T<sub>C</sub>=25℃)

Parameter	Symbol	RM6N800HD RM6N800T2	RM6N800T1	Unit
Drain-Source Voltage (Vgs=0V)	V <sub>DS</sub>	800		V
Gate-Source Voltage (VDS=0V), AC(f>1HZ)	V <sub>G</sub> s	±	30	V
Continuous Drain Current at T <sub>C</sub> =25°C	I <sub>D (DC)</sub>	6	6*	Α
Continuous Drain Current at T <sub>C</sub> =100°C	I <sub>D (DC)</sub>	3.8	3.8*	Α
Pulsed drain current (Note 1)	I <sub>DM (pluse)</sub>	24	24*	Α
Maximum Power Dissipation(T <sub>C</sub> =25 <sup>°</sup> ℂ)	P <sub>D</sub>	98	32.4	W
Derate above 25°C		0.78	0.26	W/°C
Single pulse avalanche energy (Note2)	Eas	100		mJ
Avalanche current <sup>(Note 1)</sup>	I <sub>AR</sub>	5		Α
Repetitive Avalanche energy , $t_{\text{AR}}$ limited by $T_{\text{jmax}}$ (Note 1)	E <sub>AR</sub>	0	.3	mJ

Parameter	Symbol	RM6N800HD RM6N800T2	RM6N800T1	Unit
Drain Source voltage slope, V <sub>DS</sub> ≤480 V,	dv/dt	50		V/ns
Reverse diode dv/dt, $V_{DS} \le 480 \text{ V,I}_{SD} < I_{D}$	dv/dt	1	5	V/ns
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55	+150	°C

<sup>\*</sup> limited by maximum junction temperature

#### **Table 2. Thermal Characteristic**

Parameter	Symbol	RM6N800HD RM6N800T2	RM6N800T1	Unit
Thermal Resistance, Junction-to-Case (Maximum)	R <sub>thJC</sub>	1.28	3.86	°C /W
Thermal Resistance, Junction-to-Ambient (Maximum)	R <sub>thJA</sub>	62	80	°C /W

Table 3. Electrical Characteristics (TA=25℃unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
On/off states					l .	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	800			V
Zero Gate Voltage Drain Current(Tc=25℃)	I <sub>DSS</sub>	V <sub>DS</sub> =800V,V <sub>GS</sub> =0V			1	μA
Zero Gate Voltage Drain Current(Tc=125°C)	I <sub>DSS</sub>	V <sub>DS</sub> =800V,V <sub>GS</sub> =0V			100	μΑ
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V,V <sub>DS</sub> =0V			±100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS},I_{D}=250\mu A$	3	3.5	4	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =4A		750	900	mΩ
Dynamic Characteristics						
Forward Transconductance	<b>g</b> FS	V <sub>DS</sub> = 20V, I <sub>D</sub> =4A		6		S
Input Capacitance	C <sub>lss</sub>	\/ -50\/\/ -0\/		1320		pF
Output Capacitance	Coss	$V_{DS}$ =50V, $V_{GS}$ =0V, F=1.0MHz		33		pF
Reverse Transfer Capacitance	C <sub>rss</sub>	F-1.UIVIDZ		2		pF
Total Gate Charge	Qg	\/ -C40\/   -CA		22.8		nC
Gate-Source Charge	$Q_{gs}$	$V_{DS}=640V,I_{D}=6A,$ $V_{GS}=10V$		7.7		nC
Gate-Drain Charge	$Q_{gd}$	V GS-10 V		6.9		nC
Switching times						
Turn-on Delay Time	t <sub>d(on)</sub>			10		nS
Turn-on Rise Time	t <sub>r</sub>	$V_{DD}$ =400 $V$ , $I_D$ =3 $A$ ,		5		nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$R_G=3\Omega,V_{GS}=10V$		53	70	nS
Turn-Off Fall Time	t <sub>f</sub>			6	9	nS
Source- Drain Diode Characteristics						
Source-drain current(Body Diode)	I <sub>SD</sub>	T <sub>C</sub> =25°C			6	Α
Pulsed Source-drain current(Body Diode)	I <sub>SDM</sub>	1 <sub>C</sub> -25 C			24	Α
Forward on voltage	V <sub>SD</sub>	Tj=25°C,I <sub>SD</sub> =6A,V <sub>GS</sub> =0V		0.9	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	Tj=25°C,I⊧=3A,		260		nS
Reverse Recovery Charge	Q <sub>rr</sub>	i j=25 C,i <sub>F</sub> =3A, di/dt=100A/μs		1.7		uC
Peak Reverse Recovery Current	I <sub>rrm</sub>	αι/αι-100/-ν μο		13		Α

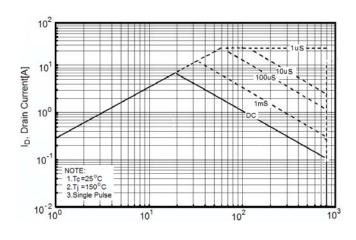
Notes: 1.Repetitive Rating: Pulse width limited by maximum junction temperature



<sup>2.</sup> Tj=25°C,VDD=50V,VG=10V, R<sub>G</sub>=25 $\Omega$ 

## RATING AND CHARACTERISTICS CURVES (RM6N800HD/T1/T2)

Figure 1. Safe operating area



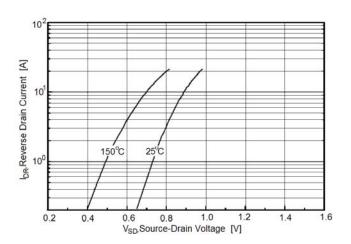


Figure 3. Source-Drain Diode Forward Voltage

Figure 5. Transfer characteristics

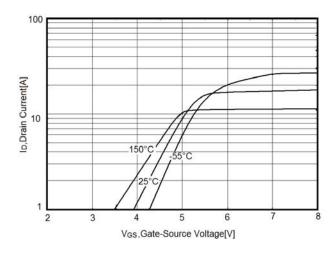


Figure 2. Safe operating area for TO-220F

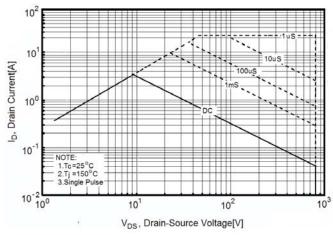


Figure 4. Output characteristics

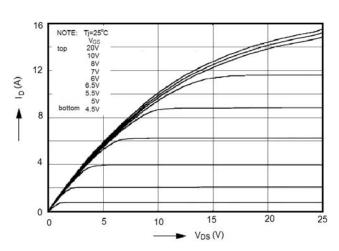
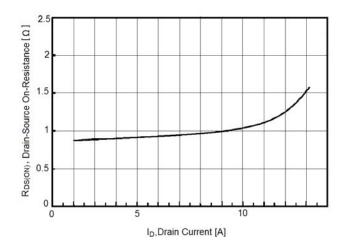


Figure 6. Static drain-source on resistance



## RATING AND CHARACTERISTICS CURVES (RM6N800HD/T1/T2)

Figure 7. R<sub>DS(ON)</sub> vs Junction Temperature

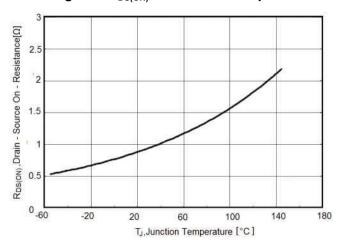


Figure 8. BV<sub>DSS</sub> vs Junction Temperature

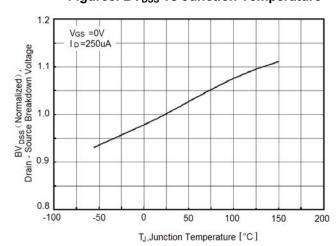


Figure 9. Maximum I<sub>D</sub> vs Junction Temperature

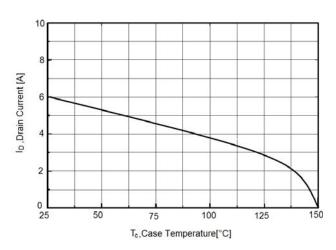


Figure 10. Gate charge waveforms

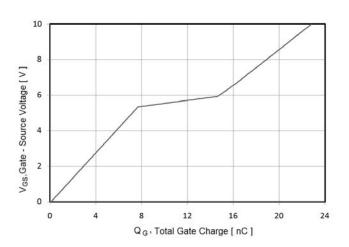


Figure11. Capacitance

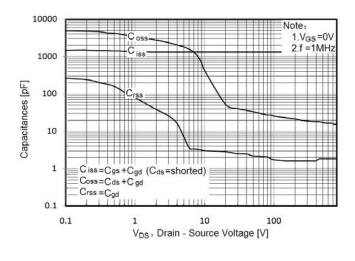
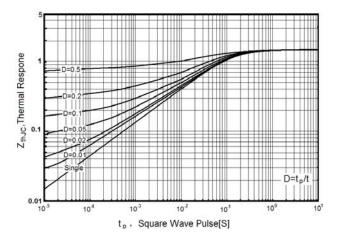


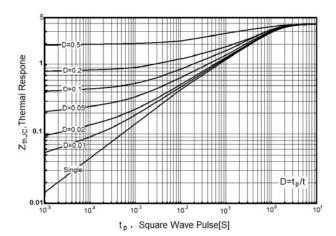
Figure 12. Transient Thermal Impedance





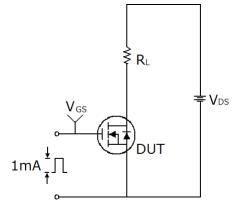
## RATING AND CHARACTERISTICS CURVES (RM6N800HD/T1/T2)

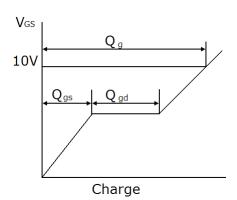
Figure 13. Transient Thermal Impedance for TO-220F



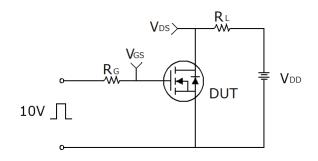
## **Test circuit**

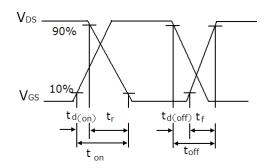
## 1) Gate charge test circuit & Waveform



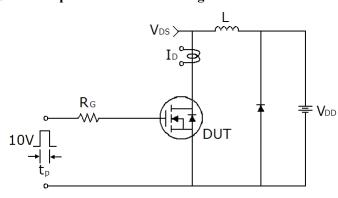


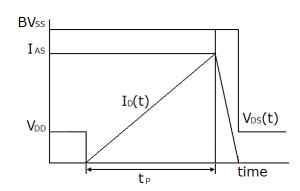
## 2) Switch Time Test Circuit:



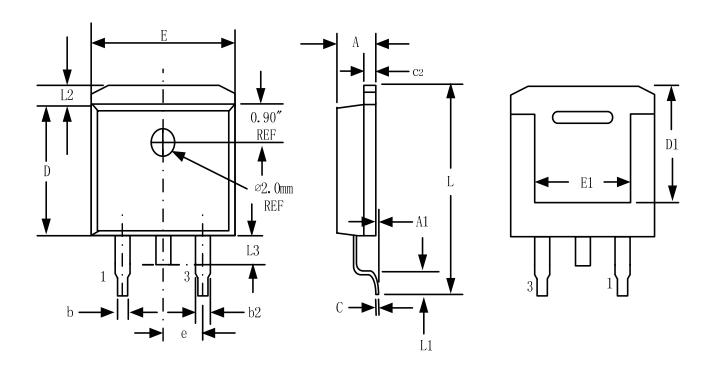


## 3) Unclamped Inductive Switching Test Circuit & Waveforms





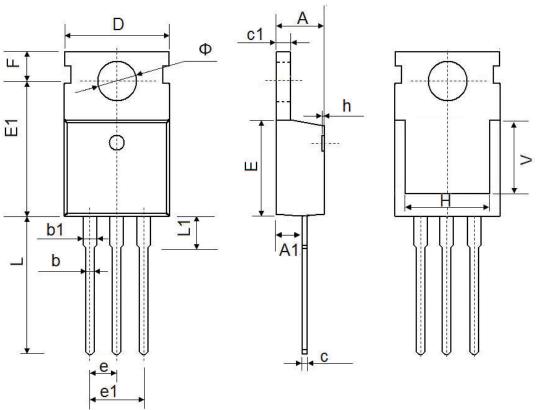
## **TO-263-3L Package Information**



Comple al	Dimensions	In Millimeters	Dimensions In Inches	
Symbol	Min.	Max.	Min.	Max.
А	4.32	4.57	0.170	0.180
A1	-	0.25		0.010
b	0.71	0.94	0.028	0.037
b2	1.15	1.40	0.045	0.055
С	0.46	0.61	0.018	0.024
c2	1.22	1.40	0.048	0.055
D	8.89	9.40	0.350	0.370
D1	8.01	8.23	0.315	0.324
Е	10.04	10.28	0.395	0.405
E1	7.88	8.08	0.310	0.318
е	2.54 BSC		0.100 BSC	
L	14.73	15.75	0.580	0.620
L1	2.29	2.79	0.090	0.110
L2	1.15	1.39	0.045	0.055
L3	1.27	1.77	0.050	0.070



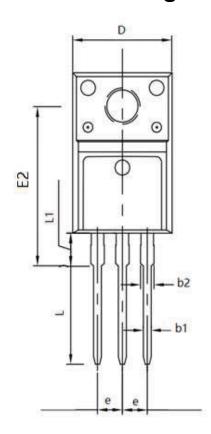
# **TO-220-3L-C Package Information**

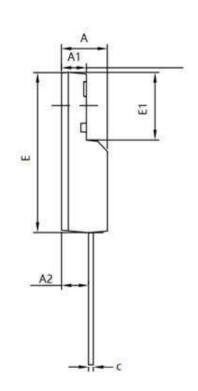


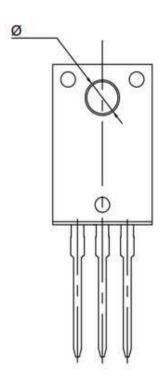
Comple of	Dimensions	In Millimeters	Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	4.400	4.600	0.173	0.181
A1	2.250	2.550	0.089	0.100
b	0.710	0.910	0.028	0.036
b1	1.170	1.370	0.046	0.054
С	0.330	0.650	0.013	0.026
c1	1.200	1.400	0.047	0.055
D	9.910	10.250	0.390	0.404
E	8.9500	9.750	0.352	0.384
E1	12.650	12.950	0.498	0.510
е	2.540 TYP.		0.100	TYP.
e1	4.980	5.180	0.196	0.204
F	2.650	2.950	0.104	0.116
Н	7.900	8.100	0.311	0.319
h	0.000	0.300	0.000	0.012
L	12.900	13.400	0.508	0.528
L1	2.850	3.250	0.112	0.128
V	7.500	REF.	0.295	REF.
Φ	3.400	3.800	0.134	0.150



# **TO-220F Package Information**







Symbol	Dimensions I	n Millimeters	eters Dimensions In Inc	
	Min.	Max.	Min.	Max.
A	4.500	4.900	0.177	0.193
A1	2.340	2.740	0.092	0.108
A2	2.560	2.960	0.101	0.117
b1	0.700	0.900	0.028	0.035
b2	1.180	1.580	0.046	0.062
С	0.400	0.600	0.016	0.024
D	9.960	10.360	0.392	0.408
E	15.670	15.970	0.617	0.629
E1	6.500	6.900	0.256	0.272
E2	15.500	16.100	0.610	0.634
е	2.540	) TYP	0.100	) TYP
Ф	3.080	3.280	0.121	0.129
L	12.640	13.240	0.498	0.521
L1	3.030	3.430	0.119	0.135

